

USSN 10/068,159

PATENT RESPONSE

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application: 10/068,159
 Filing Date: February 5, 2002
 Inventors: Hock Chuan Tan, et al.
 Title: Stacked Die In Die BGA Package
 Examiner: Thao P. Le
 Art Unit: 2818
 Attorney Docket: MTI-31608 (15225.0049)
 Confirmation No.: 8043

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CERTIFICATION UNDER 37 CFR 1.8(a) and 1.10

I hereby certify that, on the date shown below, this correspondence is being:

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- transmitted by facsimile to Fax No. (703) 308-7722 addressed to Examiner Le at the Patent and Trademark Office.

Date: July 28, 2003

Janet Dickerson

Commissioner for Patents
 P.O. Box 1450
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RESPONSE

Dear Sir:

Please see the attached.

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PATENT RESPONSE

INTRODUCTORY COMMENTS

After careful review, Applicant hereby responds to a May 27, 2003 non-final Office Action regarding the above-referenced patent application. In view of this Response, Applicant respectfully requests reconsideration of said application.

Applicant has not added new matter with this Response, and intends the scope of the invention and previously pending claims to be the same before and after this Response. Indeed, Applicant only offers this Response to clarify the invention for the Examiner, and to assist the Examiner's understanding of the same. More specifically, Applicant has not intended this Response to effectuate a narrowing of the claims, foreclose techniques that are not reasonably foreseeable at this time, or effect the applicability and scope of the Doctrine of Equivalents.

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